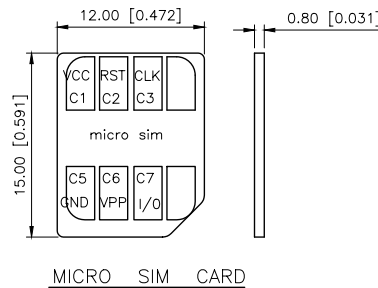
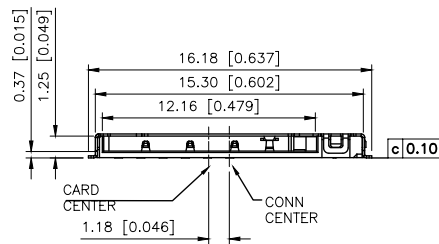
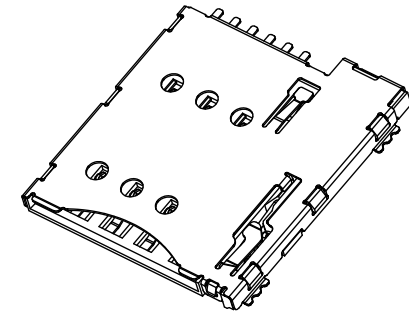
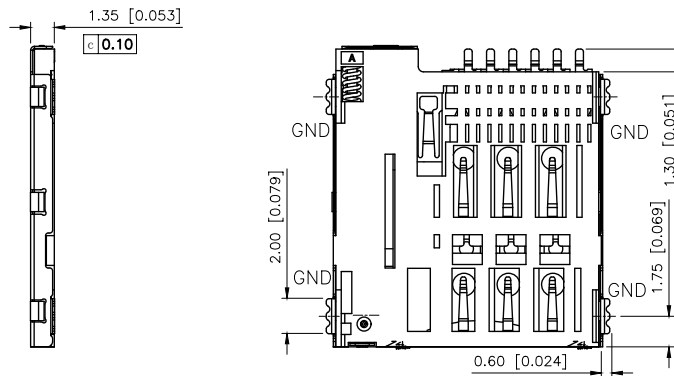
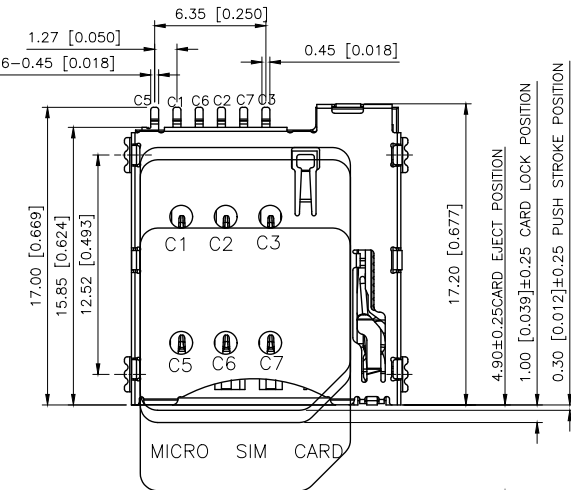
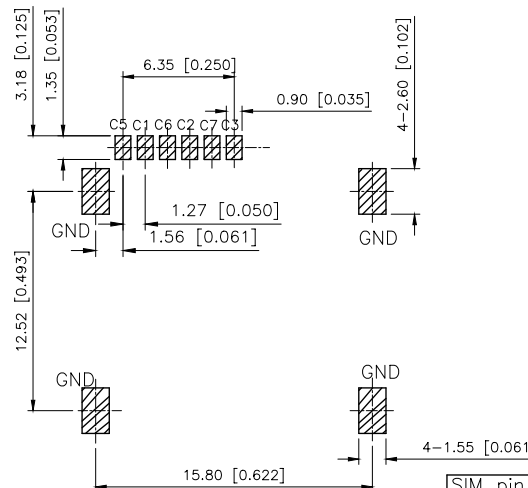


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.15	阿树



■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.



RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:
 MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS
 PLATING:
 Contact: Plated 30u" Ni Overall ,Solder Area:
 Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area
 Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100m max.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°

ITEM	PAPT	NAMF	QTY	MATERIAL	FINISHING
③	Shell	1		SUS	
②	Terminal	6		COPPER ALLOY	
①	Housing	1		HI-TEMP.PLASIC UL 94V-0	BLACK

DESIGN	阿树	VIEW:	MODEL TYPE:
CHECKED		UNIT: mm/in	SIM CARD CONN
APPROVED		SIZE: A4	PART NO.: XKSIM-002-P6
			DWG NO.: X-XKSIM-002-P6
			SCALE N/A
			PAGE 1/1
			REVISION A1

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCE	±0.05



XKB INDUSTRIAL PRECISION CO.,LIMITED